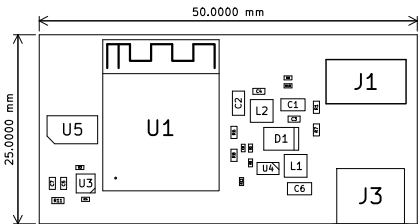


Revision Table				
Rev.	Description	Date	ECO	Signed
A	Initial Release	2025-02-09	-	



- Manufacturing Notes:
- 1. Nominal geometry is defined in the GERBER files. Drawing is for reference only.
 - 2. Hole sizes are finished dimensions.
 - 3. Manufacture board per parameters in stackup table & board characteristics table.
 - 4. Inspect PCB per IPC–A–600 Current Rev., Performance Class II.

- Assembly Notes:
- 5. See BOM for definition of components.
 - 6. See CENTROID file for nominal component positioning.
 - 7. Inspect PCBA per IPC–A–610 Current Rev, Performance Class II.

- Other Notes:
- 8. SCHEMATIC is for reference only.

Complementary Documents:
GERBER: 000001–GBR–A
BOM: 000001–BOM–A
CENTROID: 000001–CTR–A
SCHEMATIC: 000001–SCH–A

BOARD CHARACTERISTICS TABLE

Copper Layer Count:	4	Board Thickness:	1.6062 mm
Board overall dimensions:	50.0000 mm x 25.0000 mm		
Min track/spacing:	0.0000 mm / 0.2000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

STACKUP TABLE

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R
F.Silkscreen	Top Silk Screen	Not specified	–	White	1
F.Paste	Top Solder Paste		–		1
F.Mask	Top Solder Mask	Not specified	–	Green	3.8
F.Cu	copper		0.035 mm		1
Dielectric 1	prepreg	7628	0.2104 mm	Not specified	4.4
In1.Cu	copper		0.0152 mm		1
Dielectric 2	core	FR4	1.065 mm	Not specified	4.6
In2.Cu	copper		0.0152 mm		1
Dielectric 3	prepreg	7628	0.2104 mm	Not specified	4.4
B.Cu	copper		0.035 mm		1
B.Mask	Bottom Solder Mask	Not specified	–	Green	3.8
B.Paste	Bottom Solder Paste		–		1
B.Silkscreen	Bottom Silk Screen	Not specified	–	White	1

	Signature	Date	Document Number	RM DESIGNS			
Drawn By.	r.marple	2025-02-09	000001-01	Title Humidity Controller Layout Drawing			
Chk. By.			Document Type				
Apv. By.			PCB Layout				
			Responsible dept.	Rev.	Document Status	Date of Issue	Sheet
			Engineering	A			1 of 1